

Title (en)

METHOD FOR PRODUCING CONDUCTIVE STRUCTURES BY MEANS OF A PRINTING TECHNIQUE, AND ACTIVE COMPONENTS PRODUCED THEREFROM FOR INTEGRATED CIRCUITS

Title (de)

VERFAHREN ZUR ERZEUGUNG VON LEITFÄHIGEN STRUKTUREN MITTELS DRUCKTECHNIK SOWIE DARAUS HERGESTELLTE AKTIVE BAUELEMENTE FÜR INTEGRIERTE SCHALTUNGEN

Title (fr)

PROCEDE POUR REALISER DES STRUCTURES CONDUCTRICES PAR UNE TECHNIQUE DE PRESSION, COMPOSANTS ACTIFS AINSI FABRIQUES ET DESTINES A DES CIRCUITS IMPRIMES

Publication

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Application

**EP 02726090 A 20020513**

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Abstract (en)

[origin: DE10126859A1] The invention relates to a method for producing conductive structures. Said method is characterised in that strip conductors or electrodes are directly or indirectly produced in a conductive layer by means of a printing technique. The inventive method is especially suitable for producing electrodes and strip conductors in simple, fast and cost-effective ways.

[origin: DE10126859A1] Production of conducting structures comprises directly or indirectly forming conducting pathways and/or electrodes in a conducting layer using a printing technique.

IPC 1-7

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